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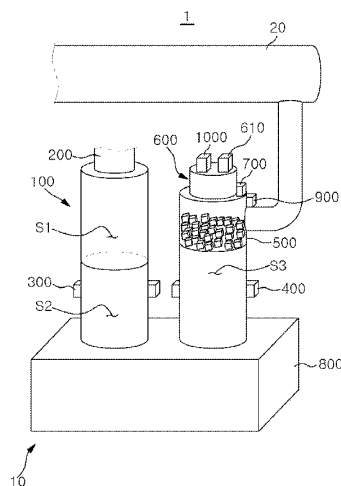
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- (54) **Title:** FACILITY FOR TREATING GAS COMPRISING A GAS COOLING APPARATUS

FIG. 1



(57) **Abstract:** A facility for treating gas comprising a gas cooling apparatus is provided. According to an embodiment of the invention, there is provided a facility for treating gas 1, comprising a flow channel 100 providing a passage through which a waste gas flows; a thermal decomposition unit 200 for thermally decomposing the waste gas flowing through the flow channel 100; a quencher 300 for cooling the waste gas passed through the thermal decomposition unit 200 to a predetermined temperature; and a cooling chamber 500 in communication with the flow channel 100 such that the waste gas passed through the quencher 300 is introduced into the cooling chamber 500, the cooling chamber 500 accommodating a solid material for cooling therewithin. The invention can achieve an advantageous effect of decreasing relative humidity of the waste gas by allowing the waste gas to undergo a cooling process using a solid material for cooling to prevent the occurrence of dew condensation in an outlet duct, resulting in increase of the efficiency for operating a gas treating facility and improvement of the efficiency of a semiconductor manufacturing process.

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